

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows:

1. (Cancelled).
2. (Cancelled).
3. (Cancelled).
4. (Cancelled).
5. (Cancelled).
6. (Cancelled).
7. (Cancelled).
8. (Cancelled).
9. (Cancelled).
10. (Cancelled).
11. (Cancelled).

12. (Original) A wafer surface treatment apparatus with a waste liquid recovery mechanism used for treating a surface of a wafer with each of a treatment liquid and a cleaning liquid, comprising: a wafer rotary holding apparatus holding a to-be-treated wafer while rotating; and a waste liquid recovery mechanism provided around the periphery of the wafer rotary holding apparatus in a vertically movable manner, wherein the waste liquid recovery mechanism is constructed of a plurality of annular waste liquid recovery troughs which are vertically movable relative to each other or one another and the annular waste liquid recovery troughs are selectively used according to kinds of the

treatment liquid and the cleaning liquid, such that the respective waste liquids are separately recovered.

13. (Original) A wafer surface treatment apparatus according to claim 12, wherein three annular waste liquid recovery troughs are employed.

14. (Original) A wafer surface treatment apparatus according to claim 12, wherein the wafer rotary holding apparatus according to claim 1 is employed.

15. (Original) A wafer surface treatment apparatus according to claim 12, wherein the wafer rotary holding apparatus according to claim 2 is employed.